

Title (en)

PULVERIZED ORGANIC SEMICONDUCTORS AND METHOD FOR VAPOR PHASE DEPOSITION ONTO A SUPPORT

Title (de)

PULVERISIERTE ORGANISCHE HALBLEITER UND VERFAHREN ZUM AUFDAMPFEN AUF EINEN TR GER

Title (fr)

SEMI-CONDUCTEUR ORGANIQUE PULVERISE ET PROCEDE DE DEPOT CHIMIQUE EN PHASE VAPEUR SUR UN SUPPORT

Publication

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Application

**EP 04727889 A 20040416**

Priority

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Abstract (en)

[origin: WO2004097955A1] The invention relates to a method for vapor phase deposition of one or several compounds onto a support by i) introducing the compound into a carrier gas stream in a solid or gaseous state, ii) providing said compound in a gaseous state in the carrier gas stream, iii) condensing the gaseous compound, iv) returning the compound condensed in step (iii) into the gaseous state, and then v) condensing the gaseous compound on the support, the carrier gas stream containing the gaseous compound(s) being cooled to a temperature that lies below the sublimation temperature of said compound(s) by adding a gas stream.

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